

IR-2551 DIV (2-3625)

**TITLE:**                    **CHIP SCALE SURFACE MOUNTED DEVICE AND**  
**PROCESS OF MANUFACTURE**

**ABSTRACT OF THE DISCLOSURE**

5                    A chip scale package has a semiconductor MOSFET die which has a top electrode surface covered with a layer of a photosensitive liquid epoxy which is photolithographically patterned to expose portions of the electrode surface and to act as a passivation layer and as a solder mask. A solderable contact layer is then formed over the passivation layer. The individual die are mounted drain side down in a metal clip or can with the drain electrode disposed coplanar with a flange extending from the can bottom.